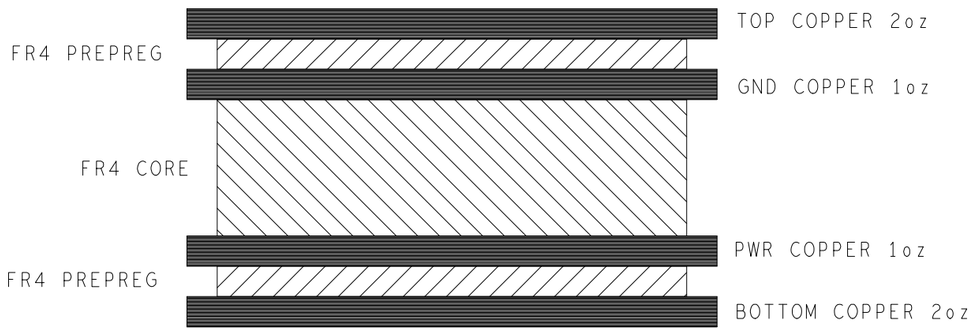
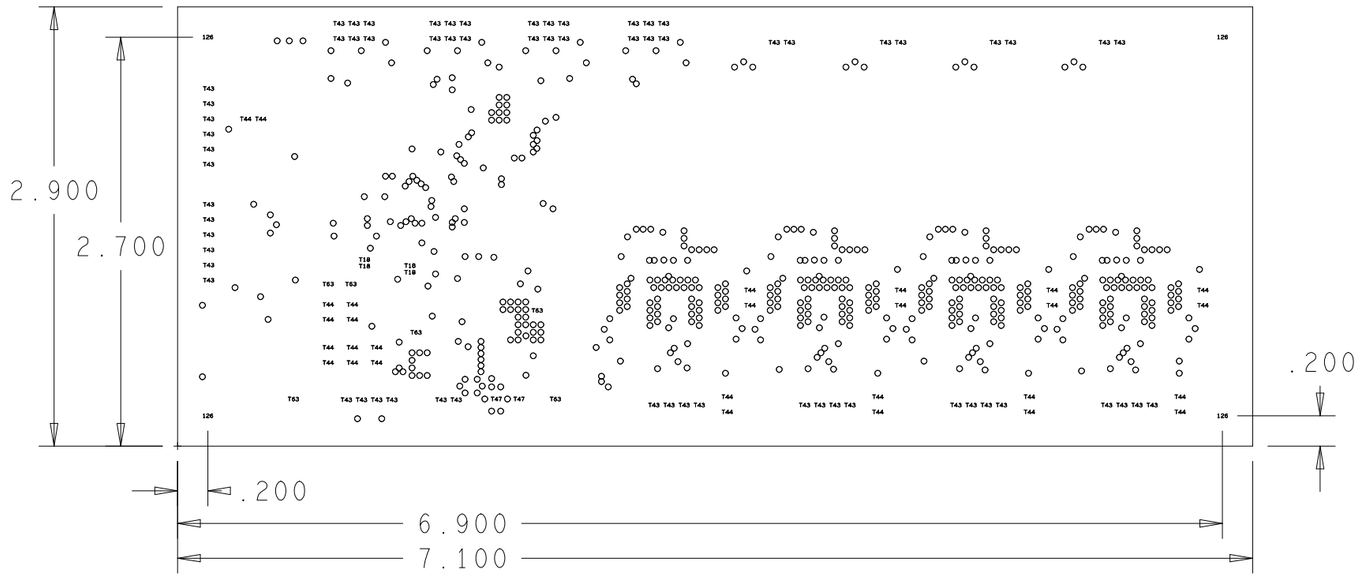
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED



PREFERRED STACK-UP

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
∘	10.0	PLATED	534
T18	18.0	PLATED	4
T43	43.0	PLATED	66
T44	44.0	PLATED	28
T47	47.0	PLATED	2
T63	63.0	PLATED	6
126	126.0	PLATED	4



CLASS II FABRICATION NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARDS SHALL BE 100% NET LIST TESTED FOR OPENS AND SHORTS PER PROVIDED IPC-D-356 NETLIST.
2. THIS BOARD SHALL BE MANUFACTURED IN ACCORDANCE WITH IPC-6012A CLASS II SPECIFICATIONS AND MEET IPC-600 CLASS II ACCEPTABILITY STANDARDS.
3. MATERIAL:
   a. FR4 PER IPC 4101B/24,/26, OR /28.
   b. SIGNAL LAYERS TO BE 2 OZ. COPPER.
   c. PLANE LAYERS TO BE 1 OZ. COPPER.
   d. OVERALL THICKNESS TO BE 0.062" +/- 10%
4. LEGEND:
   a. WHITE NON-CONDUCTIVE EPOXY INK BOTH SIDES.
5. SOLDERMASK:
   a. APPLY LIQUID PHOTO-IMAGABLE (LPI) SOLDER MASK OVER BARE COPPER PER IPC-SM-840 CLASS H, COLOR GREEN, BOTH SIDES.
6. PLATING FINISH:
   a. HOT AIR SOLDER LEVELING (HASL) SN63A SnPb SOLDER.
   ~~b. IMMERSION SILVER TAG.~~
7. PROCESS ALLOWANCES:
   a. MAXIMUM BOW AND TWIST SHALL NOT EXCEED .007" PER INCH
   b. HOLE DIMENSIONS APPLY AFTER PLATING.
   c. ALL HOLES SHALL BE LOCATED WITHIN 0.003" DIAMETER OF TRUE POSITION.
   d. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003".
   e. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 0.002".
   f. REMOVE ALL BURRS AND BREAK SHARP EDGES 0/015" MAX.
   g. CUT OUTSIDE OF 0.001" BOARD OUTLINE.

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	ESP G3 MICRO PROTOTYPE		
DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS +/- 0.02" 3 PL DECIMALS +/- 0.005" ANGLES +/- 1 Degree FRACTIONS +			MONTEREY BAY AQUARIUM RESEARCH INSTITUTE 7700 SANDHOLDT ROAD MOSS LANDING, CA		
			SIZE B	REVISION A	DWG NO 10021058
	DESIGNED BY: SCOTT JENSEN				
	LAYOUT BY: JOSE ROSAL		SCALE 1-1		SHEET 1-1